

# MECHANICAL CASE OUTLINE

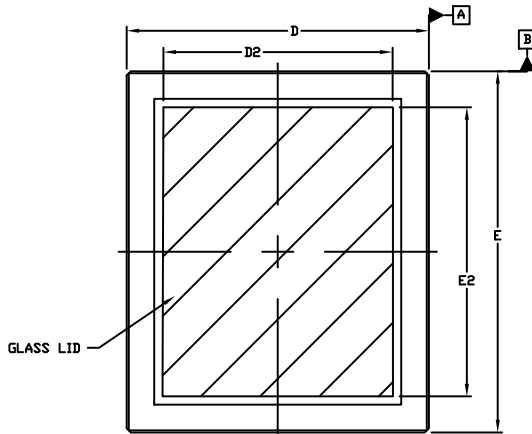
## PACKAGE DIMENSIONS

ON Semiconductor®



CPGA355, 36.10x43.10  
CASE 107DJ-01  
ISSUE O

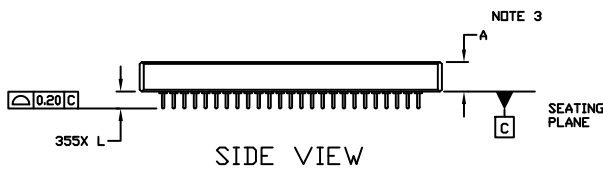
DATE 13 JUL 2011



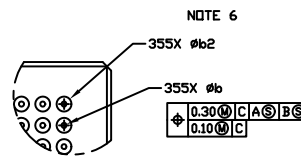
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.
6. THIS DIMENSION DEFINES THE MAXIMUM SIZE FOR THE PIN BRAZE PADS.

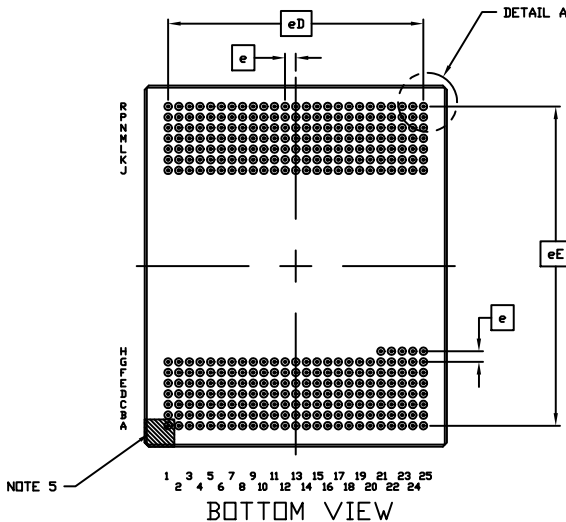


SIDE VIEW



DETAIL A  
2X SCALE

DIM	MILLIMETERS	
	MIN.	MAX.
A	3.15	3.85
b	0.25	0.35
b2	---	1.05
D	35.74	36.46
D2	27.50	REF
E	42.67	43.53
E2	34.50	REF
e	1.27	BSC
eD	30.48	BSC
eE	38.10	BSC
L	1.83	2.23

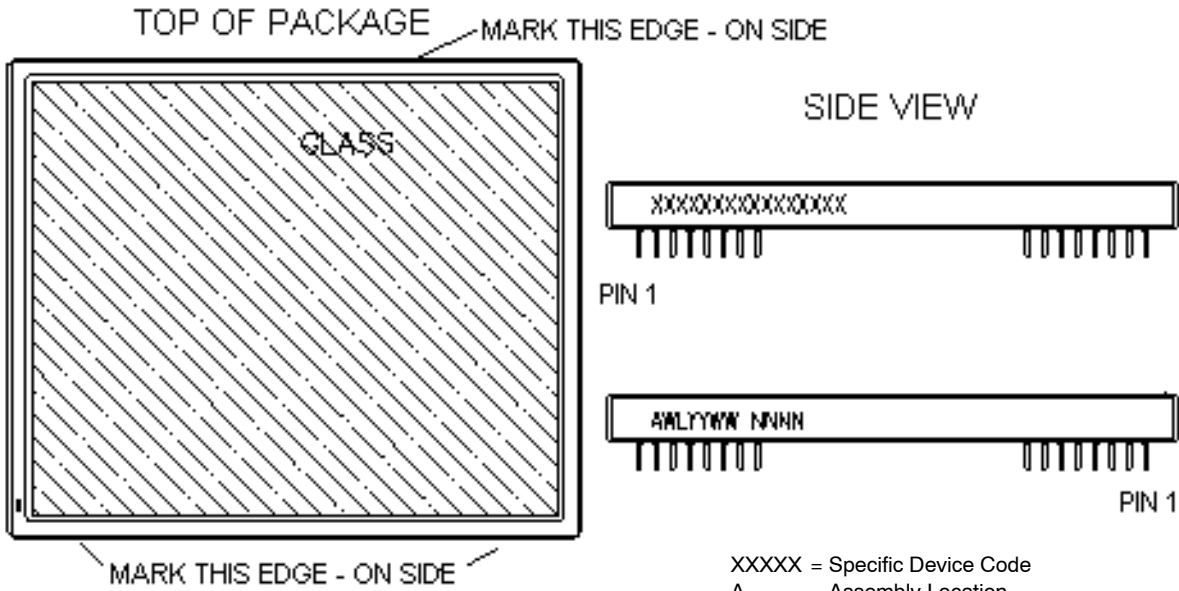


BOTTOM VIEW

GENERIC MARKING  
DIAGRAM ON PAGE 2

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STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	CPGA355, 36.10 X 43.10	PAGE 1 OF 3

GENERIC  
MARKING DIAGRAM



XXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
NNNN = Serial Number

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